



PRESS RELEASE

BE Semiconductor Industries to Host Advanced Packaging Technology Symposium at SEMICON West

Duiven, the Netherlands, July 6, 2016 - BE Semiconductor Industries N.V. (the "Company" or "Besi") (Euronext Amsterdam: BESI; OTC markets: BESIY, Nasdaq International Designation), a leading manufacturer of assembly equipment for the semiconductor industry, will host an Advanced Packaging Technology Symposium during the SEMICON West tradeshow on Wednesday July 13, 2016, from 1.00 p.m. till 5.00 p.m. at the Moscone Convention Center, South Hall, room 309.

Industry experts and Besi senior management will discuss topics in wafer level packaging, 2.5D and 3D packaging, EMI shielding (sputtering) and power package technology (sintering). A detailed agenda can be found at our website: www.besi.com.

Attendees can register for the technical seminar by sending an email to: sales@besi.com.

About Besi

Besi is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries offering high levels of accuracy, productivity and reliability at a low cost of ownership. The Company develops leading edge assembly processes and equipment for leadframe, substrate and wafer level packaging applications in a wide range of end-user markets including electronics, mobile internet, computer, automotive, industrial, LED and solar energy. Customers are primarily leading semiconductor manufacturers, assembly subcontractors and electronics and industrial companies. Besi's ordinary shares are listed on Euronext Amsterdam (symbol: BESI). Its Level 1 ADRs are listed on the OTC markets (symbol: BESIY Nasdaq International Designation) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at www.besi.com.

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